

#### **General Description**

The WSK42P10 is the highest performance trench P-Channel MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSK42P10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

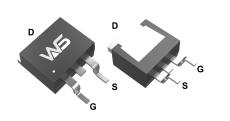
#### **Product Summery**

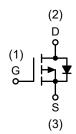
BV <sub>DSS</sub>	R <sub>DSON</sub>	l <sub>D</sub>
-100V	78mΩ	-42A

#### **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

#### **TO-263-2L Pin Configuration**





#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-42	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-19	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-75	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	89	mJ
I <sub>AS</sub>	Avalanche Current	-18.9	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	54	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	${\mathbb C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	${\mathbb C}$

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		2.3	°C/W



**P-Channel MOSFET** 

## Electrical Characteristics (TJ=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_D$ =-250uA	-100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =-1mA		-0.021		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-10A		78	95	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		-1.2	-1.7	-2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> -V <sub>DS</sub> , I <sub>D</sub> 250uA		4.08		mV/℃
I <sub>DSS</sub>	Drain Source Leakage Current	$V_{DS}$ =-48V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA
IDSS	Drain-Source Leakage Current	$V_{DS}$ =-48V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{\text{GS}}{=}\pm20\text{V}$ , $V_{\text{DS}}{=}0\text{V}$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-10A		24		S
Qg	Total Gate Charge (-4.5V)			44		
$Q_gs$	$Q_{gs}$ Gate-Source Charge $V_{DS}$ =-50V , $V_{GS}$ =-10V , $I_{D}$ =-20A			9		nC
Q <sub>gd</sub>	Gate-Drain Charge			6		
T <sub>d(on)</sub>	Turn-On Delay Time			12		
Tr	Rise Time	V <sub>DD</sub> =-30V , V <sub>GS</sub> =-10V ,		27		no
$T_{d(off)}$	Turn-Off Delay Time	$R_G$ =6Ω, $I_D$ =-10A ,RG=30Ω.		79		ns
T <sub>f</sub>	Fall Time			53		
C <sub>iss</sub>	Input Capacitance			3029		
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ =-30V , $V_{GS}$ =0V , f=1MHz		129		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			76		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.5mH , I <sub>AS</sub> =-10A	100			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-18	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0 $V$ , $I_{S}$ =-1 $A$ , $T_{J}$ =25 $^{\circ}$ C			-1.2	V

#### Note:

- 1. The data tested by surface mounted on a 1 inch $^2$  FR-4 board with 2OZ copper,  $t \le 10$  sec.
- 2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =-25V, $V_{GS}$ =-10V,L=0.5mH, $I_{AS}$ =-18.9A
- 4.The power dissipation is limited by 150 °C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



### **Typical Characteristics**

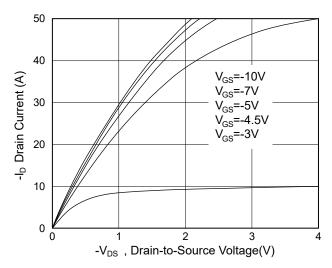


Fig.1 Typical Output Characteristics

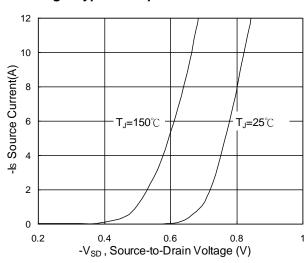


Fig.3 Typical S-D Diode Forward Voltage

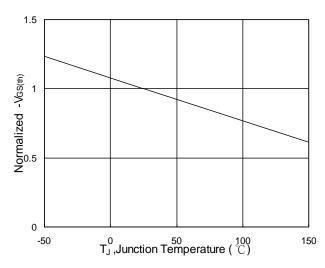


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs  $T_{\text{J}}$ 

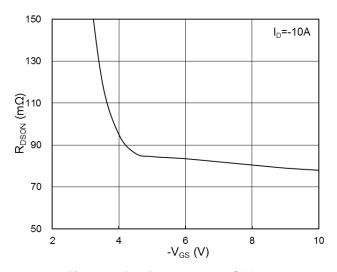


Fig.2 On-Resistance vs G-S Voltage

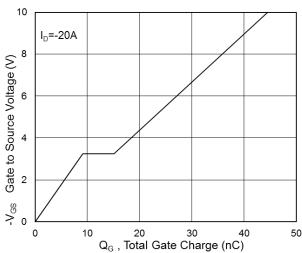


Fig.4 Gate-Charge Characteristics

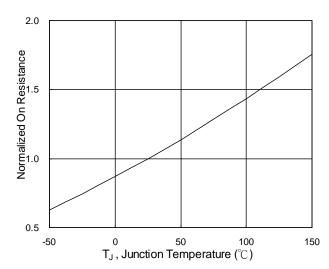
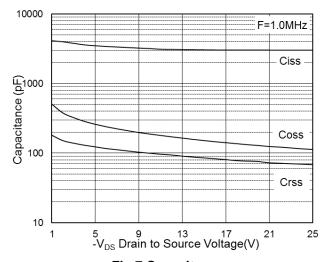


Fig.6 Normalized  $R_{\text{DSON}}$  vs  $T_{\text{J}}$ 





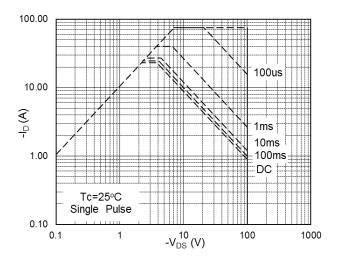


Fig.7 Capacitance

Fig.8 Safe Operating Area

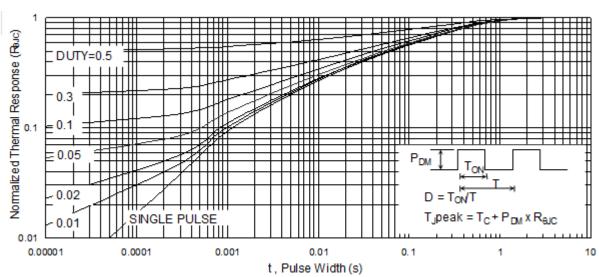
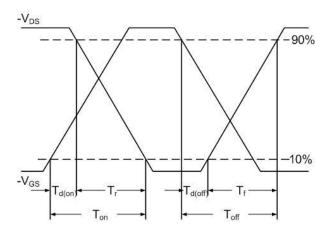


Fig.9 Normalized Maximum Transient Thermal Impedance





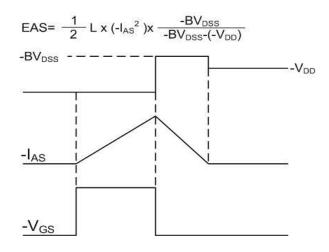
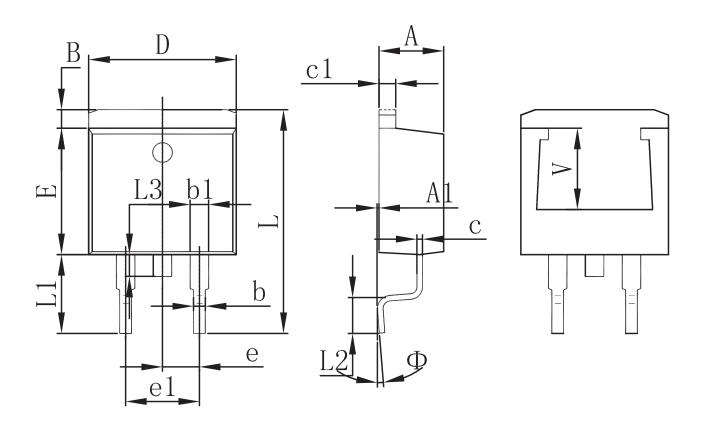


Fig.11 Unclamped Inductive Waveform



# **Packaging information**



Symbol	Dimensions Ir	n Millimeters	Dimensions Ir	n Inches
Symbol	Min.	Max.	Min.	Max.
А	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
В	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
е	2.540 TYP.		0.100	TYP.
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Ф	0°	8°	0°	8°
V	5.600	REF.	0.220REF.	



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STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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